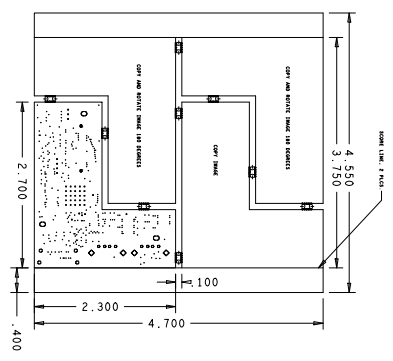


- TSLK
- SMC
- LAYER 1
- LAYER 2
- LAYER 3
- LAYER 4
- LAYER 5
- LAYER 6
- SMS
- BCLK

LAYER SCHEDULE
SCALE: NONE



9. REFER TO STACKUP FOR CONTROLLED IMPEDANCES.
8. SURFACE FINISH SHALL BE IMMERSION GOLD.
7. FINISHED BOARD SHALL BE FREE OF BURRS ON EDGES.
6. DRC'S MUST BE RUN ON THE GERBERS BEFORE BUILDING BOARDS UNLESS PRIOR APPROVAL IS GIVEN IN WRITING.
5. PLATED THRU HOLE SIZE TOLERANCES SHALL BE +/- .003 INCH.
4. UNPLATED THRU HOLE SIZE TOLERANCES SHALL BE +/- .002 INCH.
3. MINIMUM CLEARANCE ON THE BOARD SHALL BE .004 OF AN INCH.
2. MINIMUM TRACE WIDTH ON THE BOARD SHALL BE .004 OF AN INCH.
1. COPPER PLATED SURFACE CONDUCTORS SHALL BE THE EQUIVALENT OF 1 OZ. COPPER AFTER PLATING. PLANE LAYERS SHALL BE 1 OZ. COPPER. AVERAGE COPPER ON THE WALL OF THE PLATED HOLE SHALL BE .001 INCH.
1. TOTAL BOARD THICKNESS SHALL BE .062 +/- .007 INCHES.
1. ALL MATERIAL SHALL BE NEMA GRADE FR-4 OR EQUIVALENT, TG>=170C.

NOTES: UNLESS OTHERWISE SPECIFIED

DRILL CHART			
FIGURE	SIZE	PLATED	IN MILS
1	12.0	PLATED	280
2	13.0	PLATED	13
3	40.0	PLATED	8
4	51.0	PLATED	4
5	95.0	PLATED	4
6	22.0	NON-PLATED	90
7	40.0	NON-PLATED	2
8	93.0	NON-PLATED	3

DATE	9-15-17	APPROVED		<p>SPECTRUM DIGITAL</p> <p>FABRICATION DRAWING.</p> <p>J6 PLUS HOME DISPLAY ADAPTER</p>
DESIGN ENGR		CHECKED		
PROJECT ENGR		DRAFTING	SD	
ENGR MGR		ENGR		
NEXT ASSEMBLY		DO NOT SCALE DRAWING		SCALE NONE
				SHEET 1 OF 1
				518571 REV B

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